MOSFETs Silicon P-Channel MOS (U-MOSVI)

TPCF8108

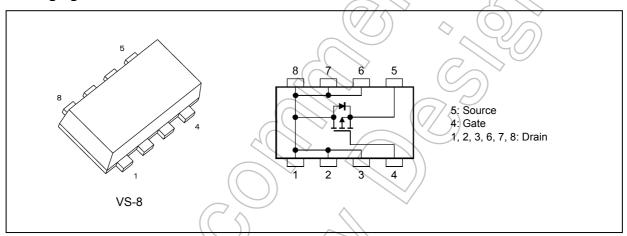
1. Applications

- · Lithium-Ion Secondary Batteries
- · Power Management Switches
- · Notebook PCs

2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 21 \text{ m}\Omega$ (typ.) ($V_{GS} = -4.5 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -20 \text{ V)}$
- (4) Enhancement mode: $V_{th} = -0.5$ to -1.2 V ($V_{DS} = -10$ V, $I_D = -0.5$ mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteristics	70	Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	-20	V
Gate-source voltage		V _{GSS}	±12]
Drain current (DC)	(Note 1)	I _D	-7	Α
Drain current (pulsed)	(Note 1)	I _{DP}	-28]
Power dissipation (t = 5 s)	(Note 2)	P _D	2.5	W
Power dissipation (t = 5 s)	(Note 3)	P _D	0.7	W
Single-pulse avalanche energy	(Note 4)	E _{AS}	31.8	mJ
Avalanche current		I _{AR}	-7	Α
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150]

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production



5. Thermal Characteristics

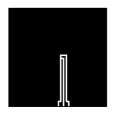
Characteristics	Symbol	Max	Unit		
Channel-to-ambient thermal resistance	(t = 5 s)	(Note 2)	R _{th(ch-a)}	50.0	°C/W
Channel-to-ambient thermal resistance	(t = 5 s)	(Note 3)	R _{th(ch-a)}	178.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150 °C.

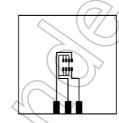
Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V_{DD} = -16 V, T_{ch} = 25 °C (initial), L = 0.5 mH, R_G = 25 Ω , I_{AR} = -7 A



 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$



 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μΑ
Drain cut-off current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			-10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = -10 mA, V _{GS} = 0 V	-20			V
Drain-source breakdown voltage (Note 5)	V _{(BR)DSX}	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$	(-12	7		
Gate threshold voltage	V_{th}	V_{DS} = -10 V, I_{D} = -0.5 mA	-0.5	<i>7</i> _	-1.2	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = -1.8 V, I _D = -1 A	/ A	45	95	mΩ
		V _{GS} = -2.5 V, I _D = -3.5 A	<i>)</i>	29	37	
		V _{GS} = -4.5 V, I _D = -3.5 A	> -	21	26	

Note 5: If a forward bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz		1320	_	pF
Reverse transfer capacitance	C _{rss}			180	_	
Output capacitance	C _{oss}		/9)	210	_	
Switching time (rise time)	t _r	See Fig. 6.2.1	\sim	8.6	_	ns
Switching time (turn-on time)	t _{on})) —	17	_	
Switching time (fall time)	t _f		_	42	_	
Switching time (turn-off time)	t _{off}		_	152	_	

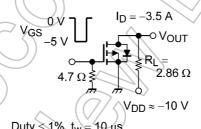


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -16 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -7 \text{ A}$	_	19		nC
Gate-source charge 1	Q _{gs1}		_	2.5		
Gate-drain charge	Q_{gd}		_	5.2		

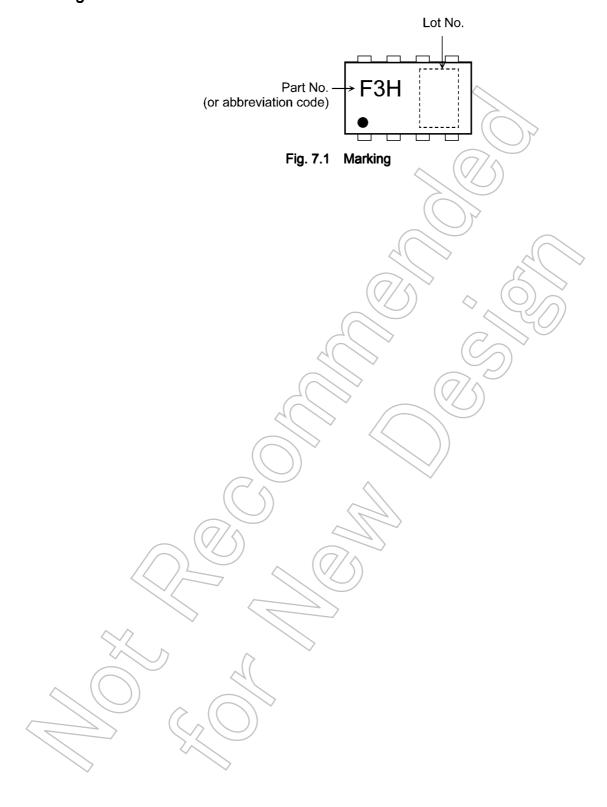
6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 6)	I _{DRP}	_	_	_	-28	Α
Diode forward voltage	'	V_{DSF}	I _{DR} = -7 A, V _{GS} = 0 V			1.2	V

Note 6: Ensure that the channel temperature does not exceed 150 °C.

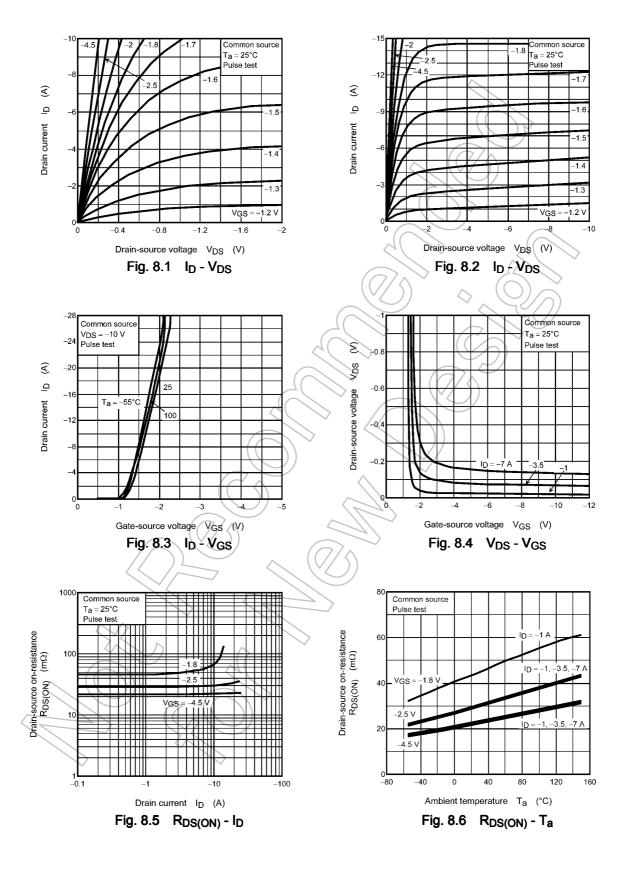


7. Marking



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8. Characteristics Curves (Note)



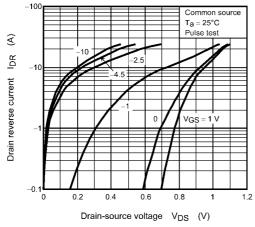


Fig. 8.7 IDR - VDS

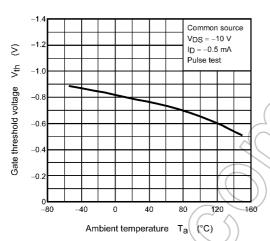


Fig. 8.9 V_{th} - T_a

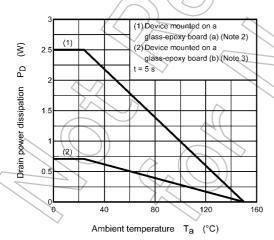


Fig. 8.11 P_D - T_a (Guaranteed Maximum)

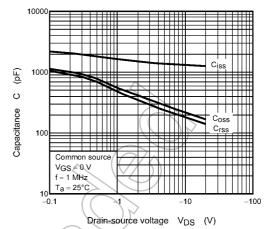


Fig. 8.8 Capacitance - V_{DS}

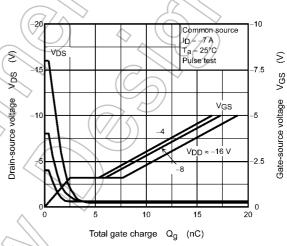


Fig. 8.10 Dynamic Input/Output Characteristics

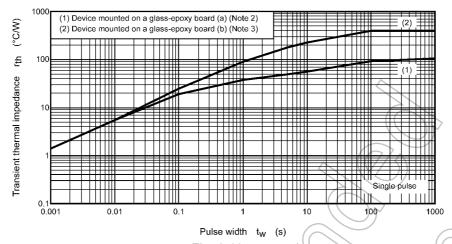


Fig. 8.12 r_{th} - t_w (Guaranteed Maximum)

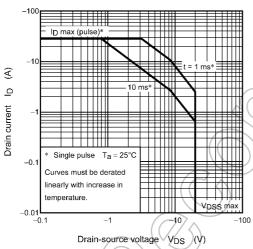


Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

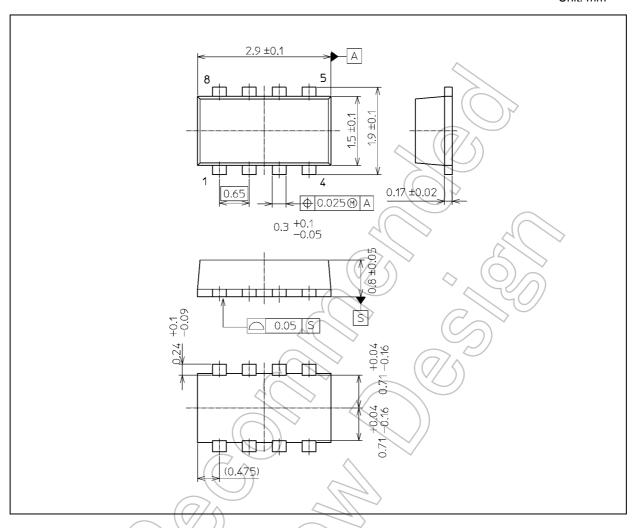
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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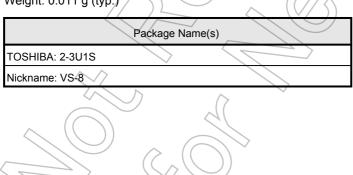


Package Dimensions

Unit: mm



Weight: 0.011 g (typ.)





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